

Title (en)
LIQUID CURABLE RESIN COMPOSITION.

Title (de)
FLÜSSIGE HÄRTBARE HARZ-ZUSAMMENSETZUNG.

Title (fr)
COMPOSITION DE RESINE LIQUIDE DURCISSABLE.

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Application
EP 93907275 A 19930309

Priority
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• US 9302037 W 19930309

Abstract (en)
[origin: WO9321248A1] A liquid curable resin composition comprising a urethane (meth)acrylate obtained by the reaction of: (A) a polyether polyol compound containing, as structural units, groups represented by the following formulas: (1) -CH₂CH₂O-, (2) -CH₂CH(R)O-, and (3) one or more groups selected from groups (a) -CH₂CH₂CH₂CH₂O-, (b), and (c) as shown above, wherein R represents an alkyl group containing two or more carbon atoms, and R<1> and R<2> are independently selected from a hydrogen atom or a methyl group; (B) a polyisocyanate compound; and (C) a (meth)acrylate compound having a hydroxy group. The composition exhibits a high curing rate, its cured material has a low Young's modulus and a high gel ratio, provides superior heat resistance and light resistance, and generates only a small amount of hydrogen gas. It is thus particularly suitable as a material for optical fiber coating.

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C08G 18/32; C08G 18/67

IPC 8 full level
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